

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YASUO KANDA</td> <td>11/21/2013</td> </tr> <tr> <td>KOICHI AMARI</td> <td>11/21/2013</td> </tr> <tr> <td>SHUNSAKU TOKITOU</td> <td>11/22/2013</td> </tr> <tr> <td>YUJI TORIGE</td> <td>11/22/2013</td> </tr> <tr> <td>TAKAYUKI ARIMA</td> <td>11/22/2013</td> </tr> </tbody> </table>		Name	Execution Date	YASUO KANDA	11/21/2013	KOICHI AMARI	11/21/2013	SHUNSAKU TOKITOU	11/22/2013	YUJI TORIGE	11/22/2013	TAKAYUKI ARIMA	11/22/2013
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<table border="1"> <tr> <td>Name:</td> <td>SONY CORPORATION</td> </tr> <tr> <td>Street Address:</td> <td>1-7-1 KONAN, MINATO-KU</td> </tr> <tr> <td>City:</td> <td>TOKYO</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>108-0075</td> </tr> </table>		Name:	SONY CORPORATION	Street Address:	1-7-1 KONAN, MINATO-KU	City:	TOKYO	State/Country:	JAPAN	Postal Code:	108-0075		
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PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14155790</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14155790								
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CORRESPONDENCE DATA													
Fax Number:	(312)876-7934												
Phone:	3128767925												
Email:	patents.us@dentons.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	DENTONS US LLP												
Address Line 1:	P.O. BOX 061080												
Address Line 4:	CHICAGO, ILLINOIS 60606-1080												
ATTORNEY DOCKET NUMBER:	09792909-9102												
NAME OF SUBMITTER:	SUSAN FARLEY												

Signature:	/susan farley/
Date:	01/15/2014
Total Attachments: 5 source=20140113_SP348952US00_Oaths#page1.tif source=20140113_SP348952US00_Oaths#page2.tif source=20140113_SP348952US00_Oaths#page3.tif source=20140113_SP348952US00_Oaths#page4.tif source=20140113_SP348952US00_Oaths#page5.tif	

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention

MEMORY ELEMENT, SEMICONDUCTOR DEVICE, AND WRITING METHOD

As the below named inventor, I hereby declare that:

This declaration is directed to:

The attached application, or

United States application or PCT international application number _____

Filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS, SONY CORPORATION with offices at 1-7-1 KONAN, MINATO-KU, TOKYO, 108-0075, JAPAN (hereinafter referred to as ASSIGNEE), is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest therein;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or misuses of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

LEGAL NAME OF INVENTOR

Inventor: YASUO KANDA

Date: November 21, 2018

Signature: Yasuo Kanda

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LEGAL NAME OF INVENTOR

Inventor: KOICHI AMARI

Date: November 21, 2013

Signature: Koichi Amari

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LEGAL NAME OF INVENTOR

Inventor: SHUNSAKU TOKITOU

Date: November 22, 2013

Signature: Shunsaku Tokitou

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LEGAL NAME OF INVENTOR

Inventor: YUJI TORIGE

Date: November 22, 2015

Signature: Yuji Torige

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LEGAL NAME OF INVENTOR

Inventor: TAKAYUKI ARIMA

Date: November 22, 2013

Signature: Takayuki Arima